

ABSTRACT

ELECTRONIC COMPONENT CLEANING APPARATUS

5 An electronic component cleaning apparatus (100) for cleaning a surface of a wafer includes: a wet cleaning unit (10), a dry cleaning unit (40), a transport unit and a control unit (17). The control unit (17): performs the wet cleaning of the surface of the wafer (80) by the wet cleaning unit (10); transports the wafer (80) that has been cleaned to the dry cleaning unit (40); performs the dry cleaning of the surface of the wafer (80) with atmospheric pressure plasma by
10 the dry cleaning unit (40); transports the wafer (80) that has been dry-cleaned to the wet cleaning unit (10); and performs a hydrogen water treatment to hydrophilize the surface of the wafer (80) using hydrogen water in which hydrogen gas is dissolved in water.

Figure 5

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